

Peak Emission Wavelength: 1050nm



Description

- Size 1206: 3.2 (L) x 1.6 (W) x 1.2 (H) mm
- Circuit substrate: glass laminated epoxy
- Devices are RoHS conform
- Lead free solderable, soldering pads: gold plated
- Taped in 8 mm blister tape, cathode to transporting perforation
- All devices are sorted into radiant intensity classes
- High radiation intensity types
- Taping: face-up (TU) or face-down (TD) possible

Absolute Maximum Ratings (Ta=25°C)



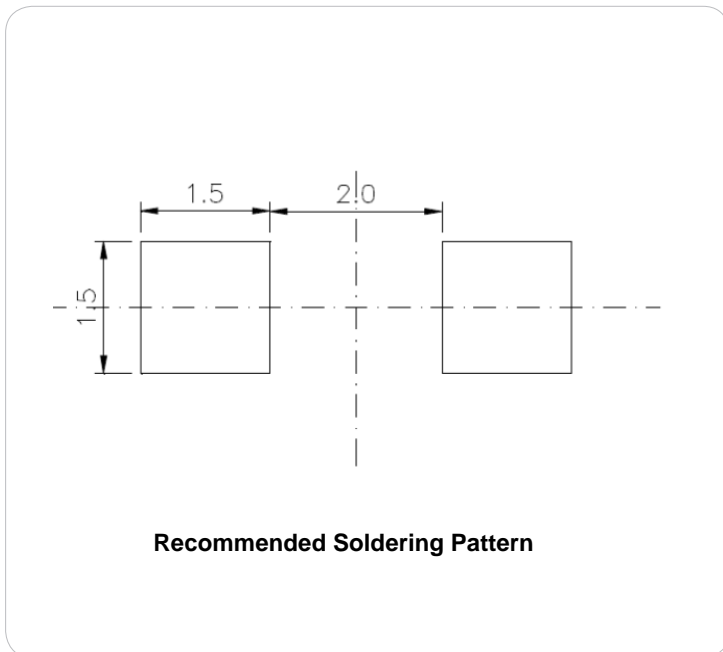
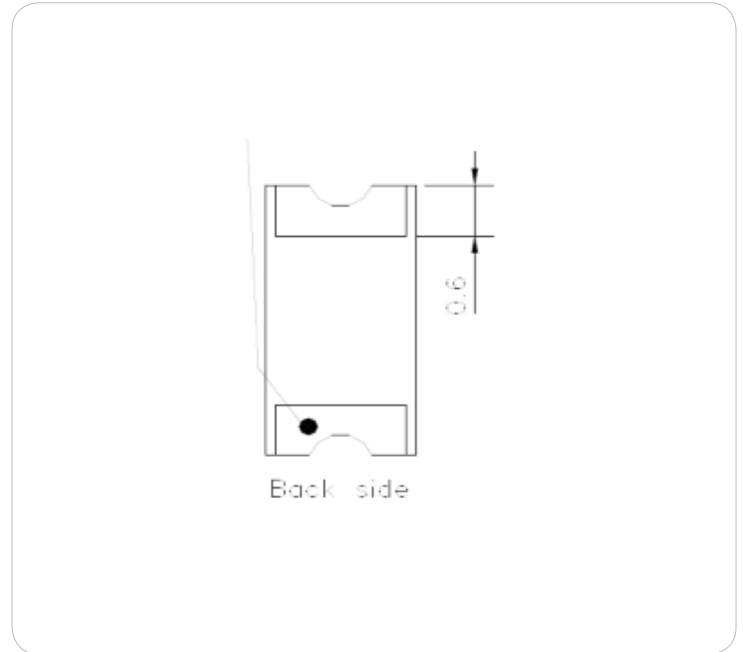
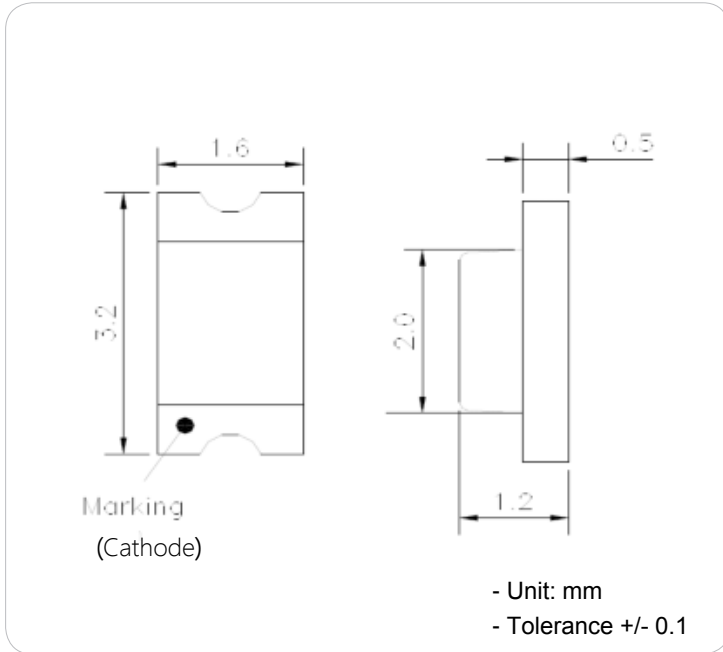
ITEMS	SYMBOL	RATINGS	UNIT
Forward DC Current	If	50	mA
Peak Forward Current *	Ifp	100	mA
Reverse Voltage	Vr	5	V
Reverse Current	Ir	100	uA
Operating Temperature	Top	-40 to +85	°C
Storage Temperature	Tst	-55 to +85	°C
Thermal Resistance	RthJA	450	K/W

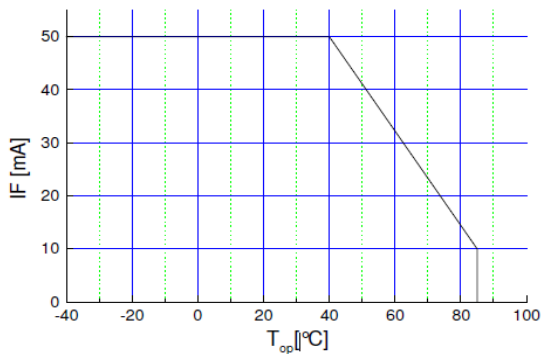
* tp ≤ 100 us, T=1:10

Electrical & Optical Characteristics (Ta = 25°C)

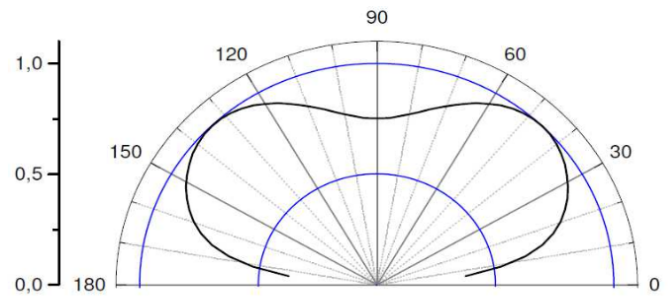
ITEMS	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT
Forward Voltage	Vf	If=50mA	--	1.22	1.50	V
Peak Wavelength	λp	If=50mA	1035	1050	1065	nm
Radiant Flux	Φe	If=50mA	3.5	--	--	mW
Radiant Intensity	Ie	If=50mA	1.12	2.0	--	mW/sr
Spectral Bandwidth	Δλ0.5	If=50mA	--	60	--	nm

Package Dimensions

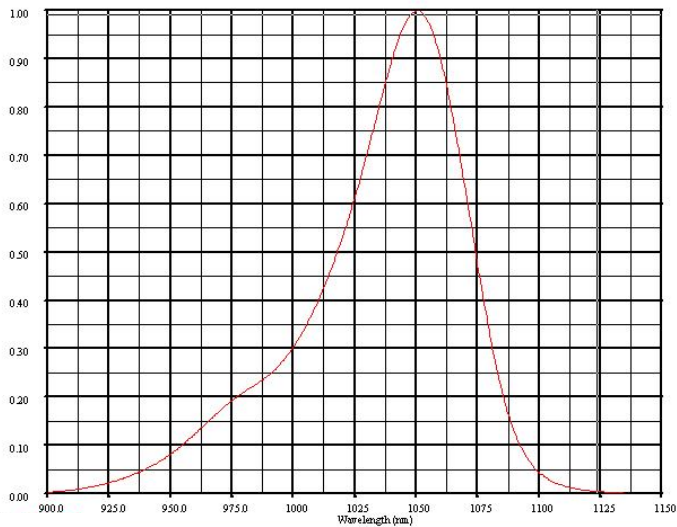




Maximal forward current (DC) characteristic

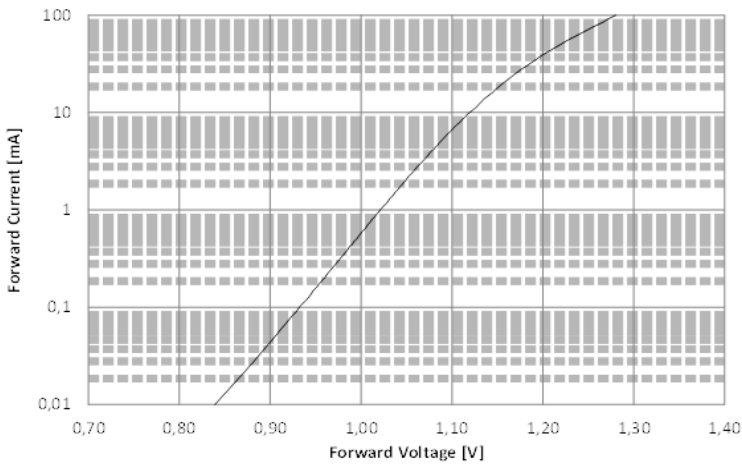


View angle

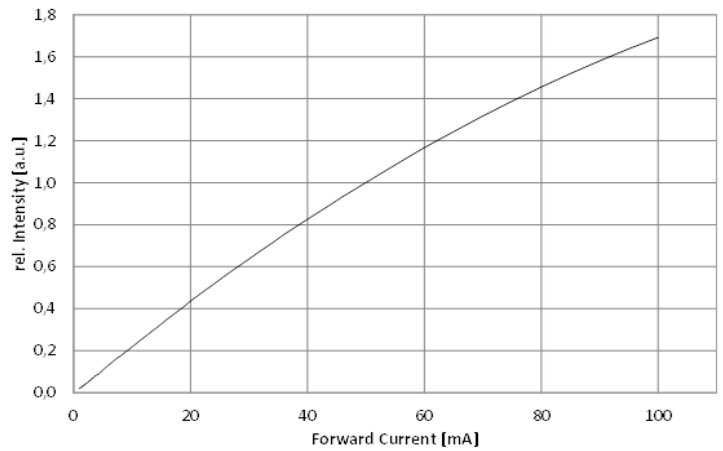


Spectral Response

Forward Current vs Forward Voltage



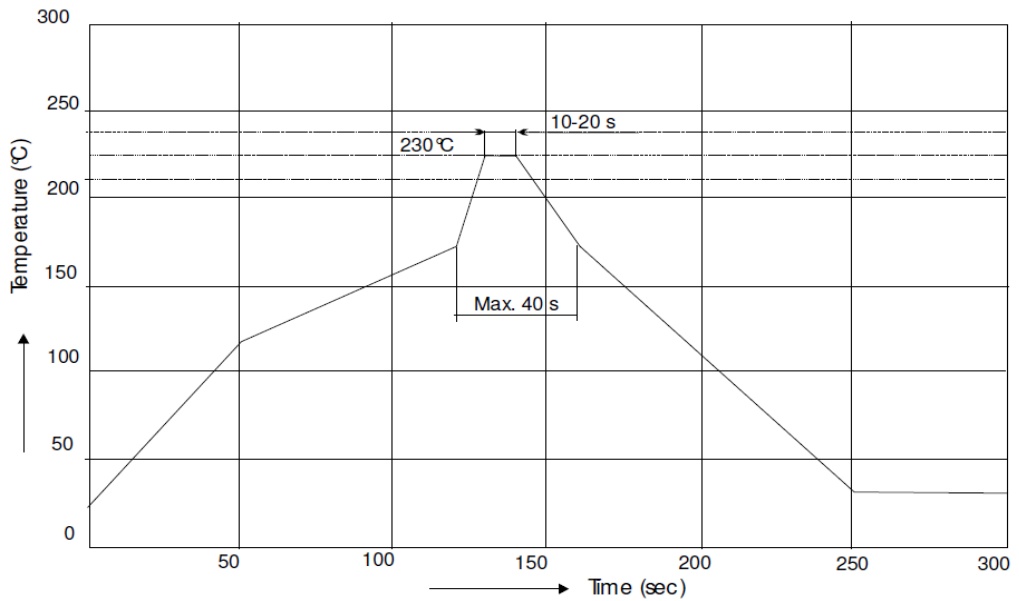
Intensity vs Forward Current



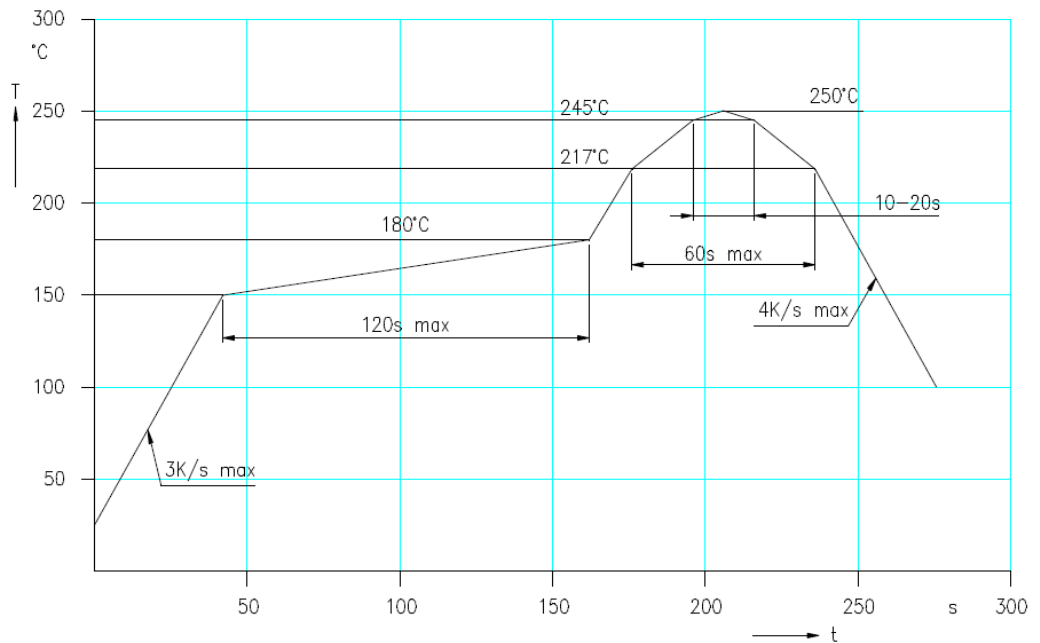
The information contained herein is subject to change without notice.

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IR reflow soldering profile



IR reflow soldering profile for lead free soldering



Manual soldering:
max power of iron 25 W / 3 s / 300°C

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